FAIRCHILD
SEMICONDUCTOR®

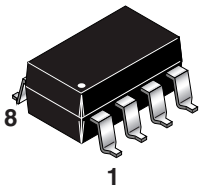
HIGH SPEED-10 MBit/s LOGIC GATE OPTOCOUPLERS

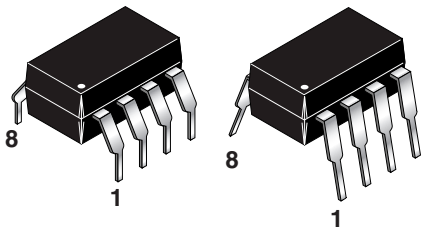
SINGLE-CHANNEL
6N137
HCPL-2601
HCPL-2611

DUAL-CHANNEL
HCPL-2630
HCPL-2631

DESCRIPTION

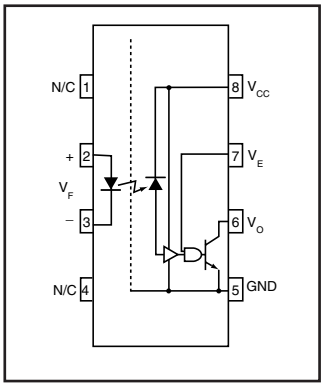
The 6N137, HCPL-2601/2611 single-channel and HCPL-2630/2631 dual-channel optocouplers consist of a 850 nm AlGaAS LED, optically coupled to a very high speed integrated photodetector logic gate with a strobable output. This output features an open collector, thereby permitting wired OR outputs. The coupled parameters are guaranteed over the temperature range of -40°C to +85°C. A maximum input signal of 5 mA will provide a minimum output sink current of 13 mA (fan out of 8).
An internal noise shield provides superior common mode rejection of typically 10 kV/µs. The HCPL- 2601 and HCPL- 2631 has a minimum CMR of 5 kV/µs.
The HCPL-2611 has a minimum CMR of 10 kV/µs.



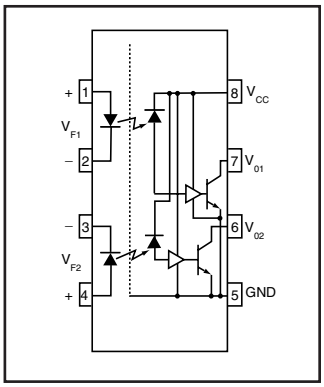


FEATURES

- Very high speed-10 MBit/s
- Superior CMR-10 kV/µs
- Double working voltage-480V
- Fan-out of 8 over -40°C to +85°C
- Logic gate output
- Strobable output
- Wired OR-open collector
- U.L. recognized (File # E90700)



6N137
HCPL-2601
HCPL-2611



HCPL-2630
HCPL-2631

APPLICATIONS

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5-volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer-peripheral interface

TRUTH TABLE
(Positive Logic)

Input	Enable	Output
H	H	L
L	H	H
H	L	H
L	L	H
H	NC	L
L	NC	H

A 0.1 µF bypass capacitor must be connected between pins 8 and 5.
(See note 1)

HIGH SPEED-10 MBit/s LOGIC GATE OPTOCOUPLERS

SINGLE-CHANNEL
6N137
HCPL-2601
HCPL-2611

DUAL-CHANNEL
HCPL-2630
HCPL-2631

ABSOLUTE MAXIMUM RATINGS (No derating required up to 85°C)

Parameter		Symbol	Value	Units
Storage Temperature		T_{STG}	-55 to +125	°C
Operating Temperature		T_{OPR}	-40 to +85	°C
Lead Solder Temperature		T_{SOL}	260 for 10 sec	°C
EMITTER				
DC/Average Forward Input Current	Single channel	I_F	50	mA
	Dual channel (Each channel)		30	
Enable Input Voltage Not to exceed V_{CC} by more than 500 mV	Single channel	V_E	5.5	V
Reverse Input Voltage	Each channel	V_R	5.0	V
Power Dissipation	Single channel	P_I	100	mW
	Dual channel (Each channel)		45	
DETECTOR				
Supply Voltage		V_{CC} (1 minute max)	7.0	V
Output Current	Single channel	I_O	50	mA
	Dual channel (Each channel)		50	
Output Voltage	Each channel	V_O	7.0	V
Collector Output Power Dissipation	Single channel	P_O	85	mW
	Dual channel (Each channel)		60	

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Units
Input Current, Low Level	I_{FL}	0	250	µA
Input Current, High Level	I_{FH}	*6.3	15	mA
Supply Voltage, Output	V_{CC}	4.5	5.5	V
Enable Voltage, Low Level	V_{EL}	0	0.8	V
Enable Voltage, High Level	V_{EH}	2.0	V_{CC}	V
Low Level Supply Current	T_A	-40	+85	°C
Fan Out (TTL load)	N		8	

* 6.3 mA is a guard banded value which allows for at least 20 % CTR degradation. Initial input current threshold value is 5.0 mA or less

ELECTRICAL CHARACTERISTICS (T_A = -40°C to +85°C Unless otherwise specified.)

INDIVIDUAL COMPONENT CHARACTERISTICS

Parameter		Test Conditions	Symbol	Min	Typ**	Max	Unit
EMITTER		(I_F = 10 mA)	V_F			1.8	V
Input Forward Voltage		T_A =25°C			1.4	1.75	
Input Reverse Breakdown Voltage		(I_R = 10 µA)	B_{VR}	5.0			V
Input Capacitance		(V_F = 0, f = 1 MHz)	C_{IN}		60		pF
Input Diode Temperature Coefficient		(I_F = 10 mA)	$\Delta V_F/\Delta T_A$		-1.4		mV/°C
DETECTOR							
High Level Supply Current	Single Channel	(V_{CC} = 5.5 V, I_F = 0 mA)	I_{CCH}		7	10	mA
	Dual Channel	(V_E = 0.5 V)			10	15	
Low Level Supply Current	Single Channel	(V_{CC} = 5.5 V, I_F = 10 mA)	I_{CCL}		9	13	mA
	Dual Channel	(V_E = 0.5 V)			14	21	
Low Level Enable Current		(V_{CC} = 5.5 V, V_E = 0.5 V)	I_{EL}		-0.8	-1.6	mA
High Level Enable Current		(V_{CC} = 5.5 V, V_E = 2.0 V)	I_{EH}		-0.6	-1.6	mA
High Level Enable Voltage		(V_{CC} = 5.5 V, I_F = 10 mA)	V_{EH}	2.0			V
Low Level Enable Voltage		(V_{CC} = 5.5 V, I_F = 10 mA) (Note 3)	V_{EL}			0.8	V

SWITCHING CHARACTERISTICS (T_A = -40°C to +85°C, V_{CC} = 5 V, I_F = 7.5 mA Unless otherwise specified.)

AC Characteristics	Test Conditions	Symbol	Min	Typ**	Max	Unit
Propagation Delay Time	(Note 4) (T_A =25°C)	T_{PLH}	20	45	75	ns
to Output High Level	(R_L = 350 Ω, C_L = 15 pF) (Fig. 12)				100	
Propagation Delay Time	(Note 5) (T_A =25°C)	T_{PHL}	25	45	75	ns
to Output Low Level	(R_L = 350 Ω, C_L = 15 pF) (Fig. 12)				100	
Pulse Width Distortion	(R_L = 350 Ω, C_L = 15 pF) (Fig. 12)	$\lvert T_{PHL}-T_{PLH}\rvert$		3	35	ns
Output Rise Time (10-90%)	(R_L = 350 Ω, C_L = 15 pF) (Note 6) (Fig. 12)	t_r		50		ns
Output Fall Time (90-10%)	(R_L = 350 Ω, C_L = 15 pF) (Note 7) (Fig. 12)	t_f		12		ns
Enable Propagation Delay Time to Output High Level	(I_F = 7.5 mA, V_{EH} = 3.5 V) (R_L = 350 Ω, C_L = 15 pF) (Note 8) (Fig. 13)	t_{ELH}		20		ns
Enable Propagation Delay Time to Output Low Level	(I_F = 7.5 mA, V_{EH} = 3.5 V) (R_L = 350 Ω, C_L = 15 pF) (Note 9) (Fig. 13)	t_{EHL}		20		ns
Common Mode Transient Immunity (at Output High Level)	(T_A =25°C) $\lvert V_{CM}\rvert$ = 50 V, (Peak) (I_F = 0 mA, V_{OH} (Min.) = 2.0 V)	$\lvert CM_H\rvert$				V/µs
	6N137, HCPL-2630 (R_L = 350 Ω) (Note 10)			10,000		
	HCPL-2601, HCPL-2631 (Fig. 14)		5000	10,000		
	HCPL-2611 $\lvert V_{CM}\rvert$ = 400 V		10,000	15,000		
Common Mode Transient Immunity (at Output Low Level)	(R_L = 350 Ω) (I_F = 7.5 mA, V_{OL} (Max.) = 0.8 V)	$\lvert CM_L\rvert$				V/µs
	6N137, HCPL-2630 $\lvert V_{CM}\rvert$ = 50 V (Peak)			10,000		
	HCPL-2601, HCPL-2631 (T_A =25°C) (Note 11) (Fig. 14)		5000	10,000		
	HCPL-2611 (T_A =25°C) $\lvert V_{CM}\rvert$ = 400 V		10,000	15,000		

TRANSFER CHARACTERISTICS (T_A = -40°C to +85°C Unless otherwise specified.)

DC Characteristics	Test Conditions	Symbol	Min	Typ**	Max	Unit
High Level Output Current	(V_{CC} = 5.5 V, V_O = 5.5 V) (I_F = 250 µA, V_E = 2.0 V) (Note 2)	I_{OH}			100	µA
Low Level Output Current	(V_{CC} = 5.5 V, I_F = 5 mA) (V_E = 2.0 V, I_{CL} = 13 mA) (Note 2)	V_{OL}		.35	0.6	V
Input Threshold Current	(V_{CC} = 5.5 V, V_O = 0.6 V, V_E = 2.0 V, I_{OL} = 13 mA)	I_{FT}		3	5	mA

ISOLATION CHARACTERISTICS (T_A = -40°C to +85°C Unless otherwise specified.)

Characteristics	Test Conditions	Symbol	Min	Typ**	Max	Unit
Input-Output Insulation Leakage Current	(Relative humidity = 45%) (T_A = 25°C, t = 5 s) (V_{I-O} = 3000 VDC) (Note 12)	I_{I-O}			1.0*	µA
Withstand Insulation Test Voltage	(RH < 50%, T_A = 25°C) (Note 12) (t = 1 min.)	V_{ISO}	2500			V_{RMS}
Resistance (Input to Output)	(V_{I-O} = 500 V) (Note 12)	R_{I-O}		10^{12}		Ω
Capacitance (Input to Output)	(f = 1 MHz) (Note 12)	C_{I-O}		0.6		pF

** All typical values are at V_{CC} = 5 V, T_A = 25°C

NOTES

1. The V_{CC} supply to each optoisolator must be bypassed by a 0.1µF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package V_{CC} and GND pins of each device.
2. Each channel.
3. Enable Input - No pull up resistor required as the device has an internal pull up resistor.
4. t_{PLH} - Propagation delay is measured from the 3.75 mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
5. t_{PHL} - Propagation delay is measured from the 3.75 mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
6. t_r - Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.
7. t_f - Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.
8. t_{ELH} - Enable input propagation delay is measured from the 1.5 V level on the HIGH to LOW transition of the input voltage pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
9. t_{EHL} - Enable input propagation delay is measured from the 1.5 V level on the LOW to HIGH transition of the input voltage pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
10. CM_H - The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the high state (i.e., V_{OUT} > 2.0 V). Measured in volts per microsecond (V/µs).
11. CM_L - The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the low output state (i.e., V_{OUT} < 0.8 V). Measured in volts per microsecond (V/µs).
12. Device considered a two-terminal device: Pins 1,2,3 and 4 shorted together, and Pins 5,6,7 and 8 shorted together.

TYPICAL PERFORMANCE CURVES

Fig.1 Low Level Output Voltage vs. Ambient Temperature

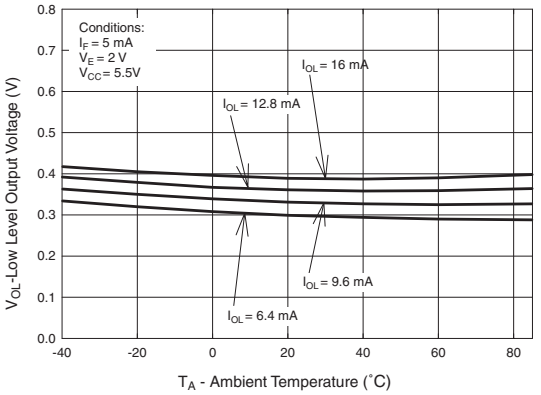


Fig. 2 Input Diode Forward Voltage vs. Forward Current

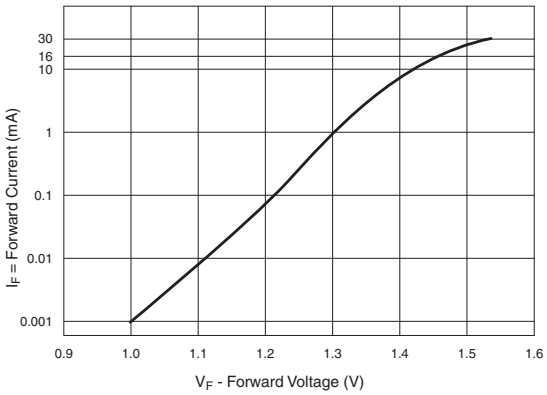


Fig.3 Switching Time vs. Forward Current

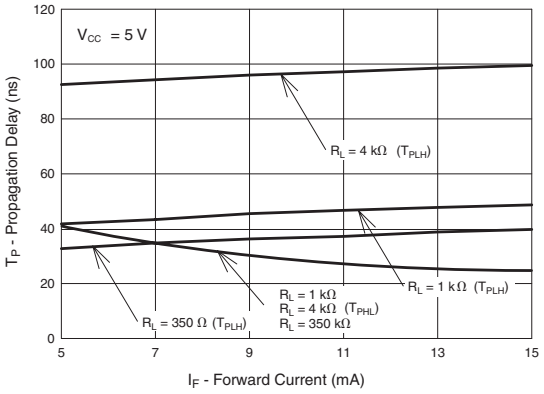


Fig. 4 Low Level Output Current vs. Ambient Temperature

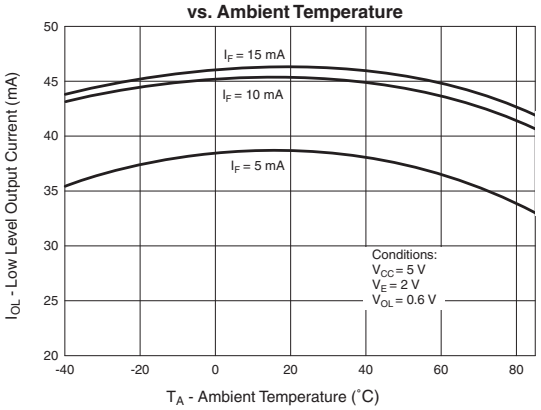


Fig. 5 Input Threshold Current vs. Ambient Temperature

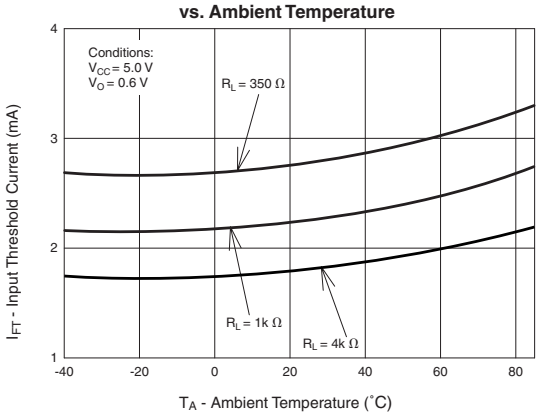


Fig. 6 Output Voltage vs. Input Forward Current

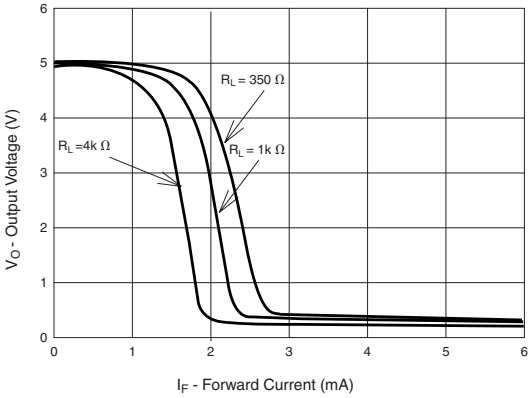


Fig. 7 Pulse Width Distortion vs. Temperature

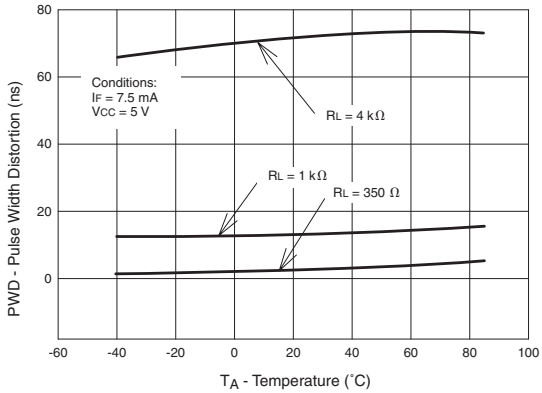


Fig. 8 Rise and Fall Time vs. Temperature

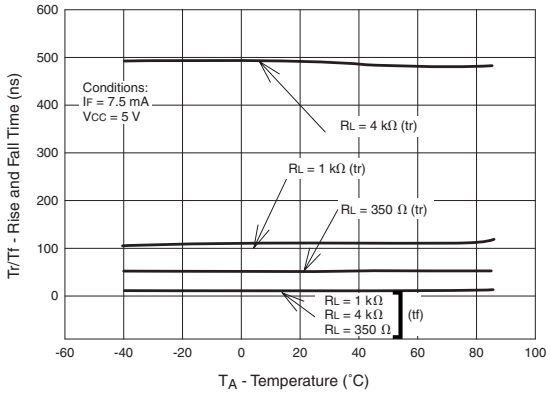


Fig. 9 Enable Propagation Delay vs. Temperature

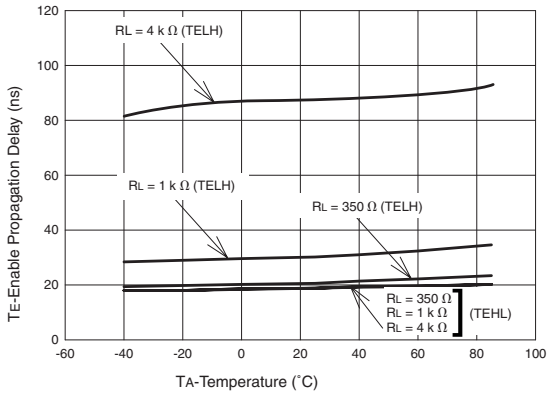


Fig. 10 Switching Time vs. Temperature

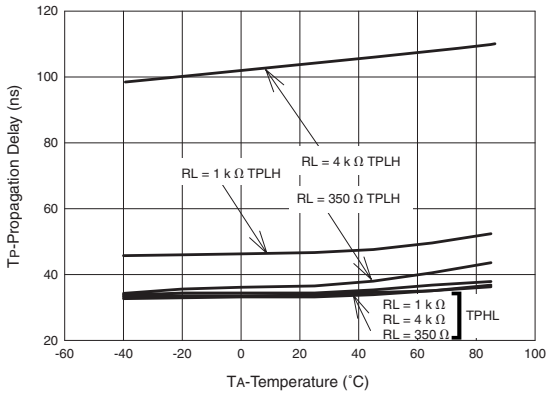
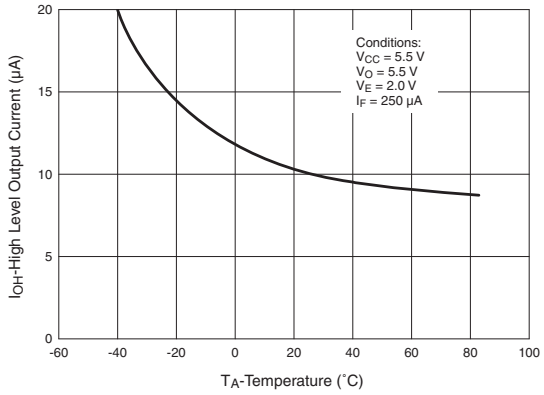


Fig. 11 High Level Output Current vs. Temperature



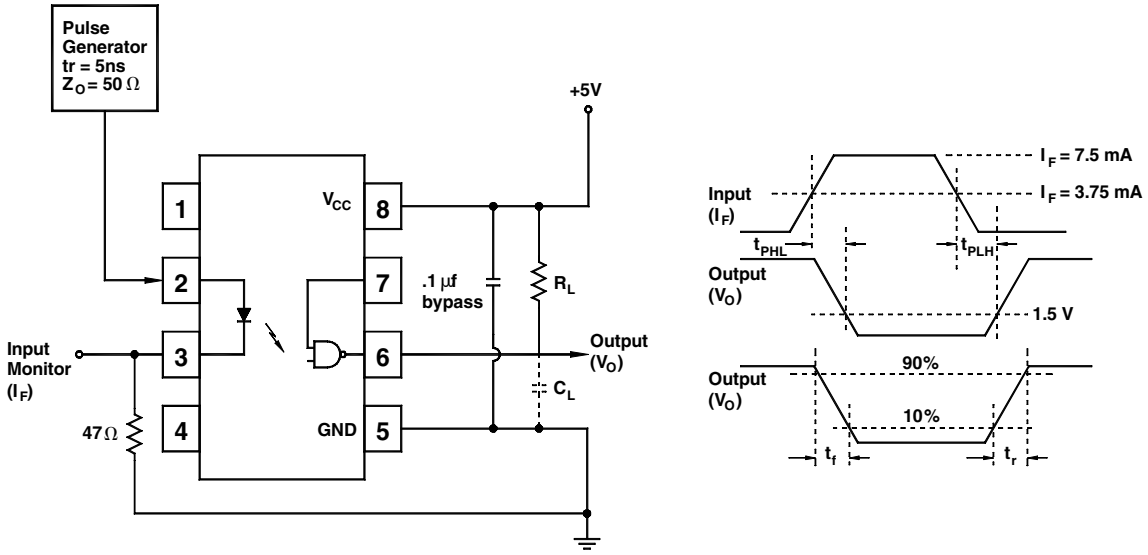


Fig. 12 Test Circuit and Waveforms for t_{PLH}, t_{PHL}, t_r and t_f.

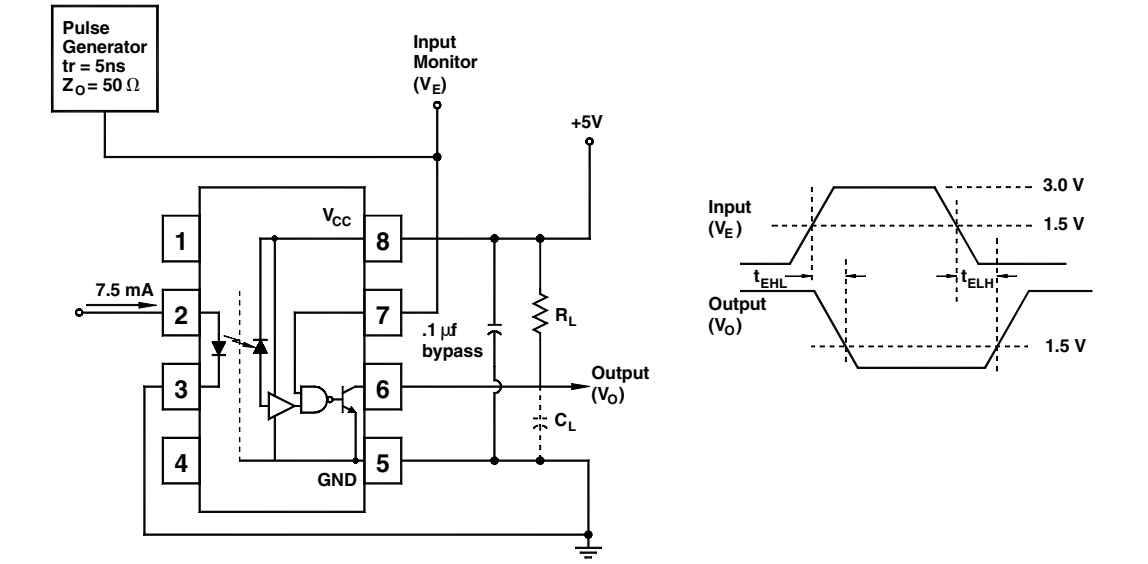


Fig. 13 Test Circuit t_{EHL} and t_{ELH}.

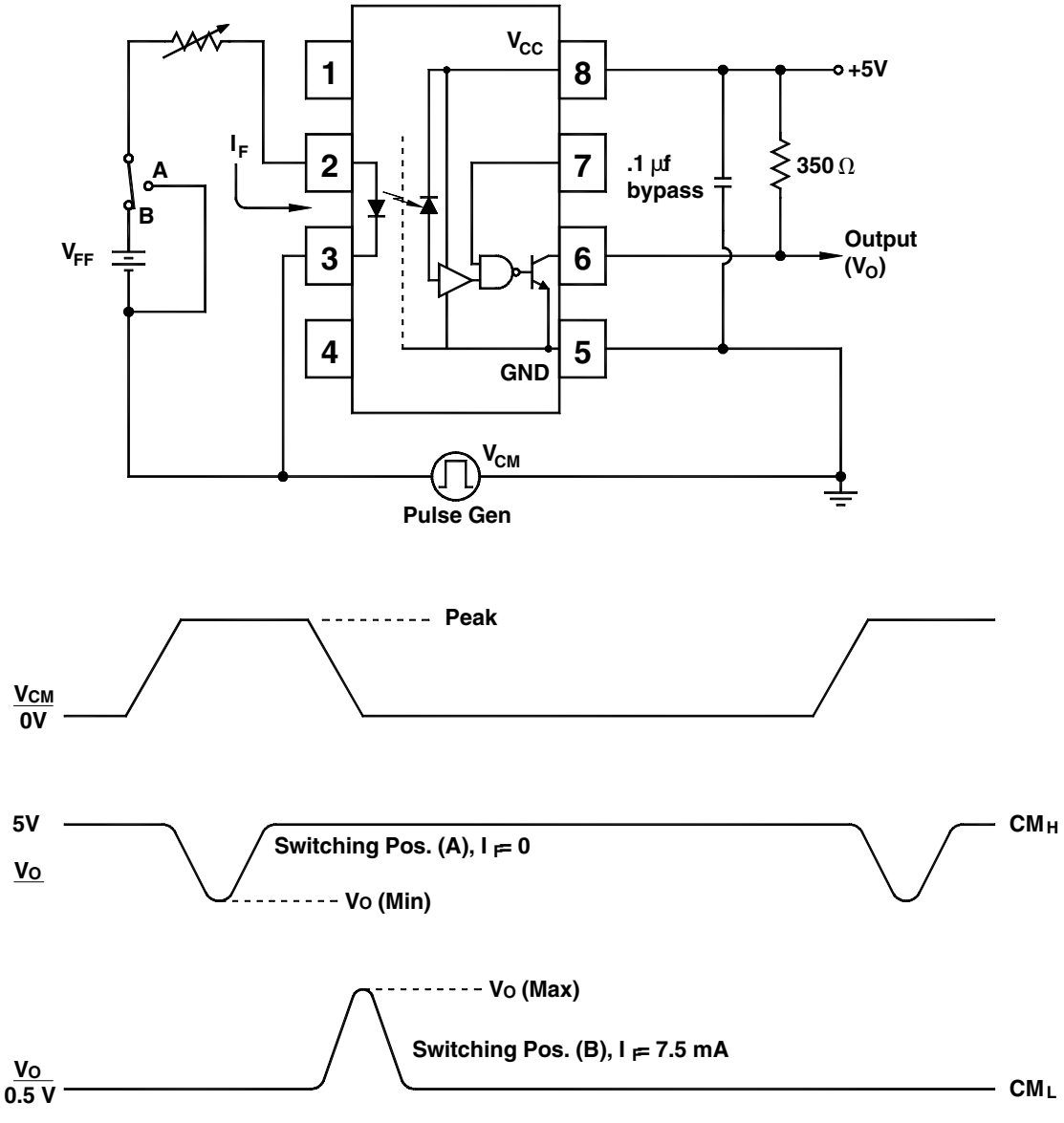
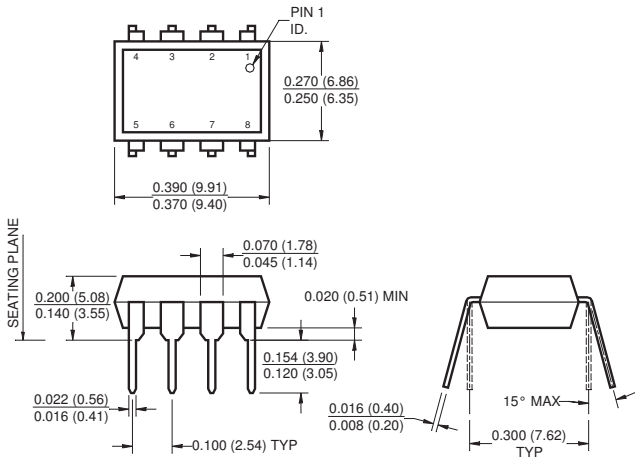


Fig. 14 Test Circuit Common Mode Transient Immunity

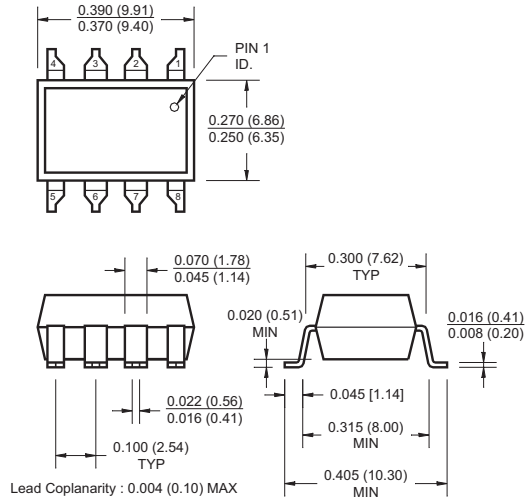
SINGLE-CHANNEL
6N137
HCPL-2601
HCPL-2611

DUAL-CHANNEL
HCPL-2630
HCPL-2631

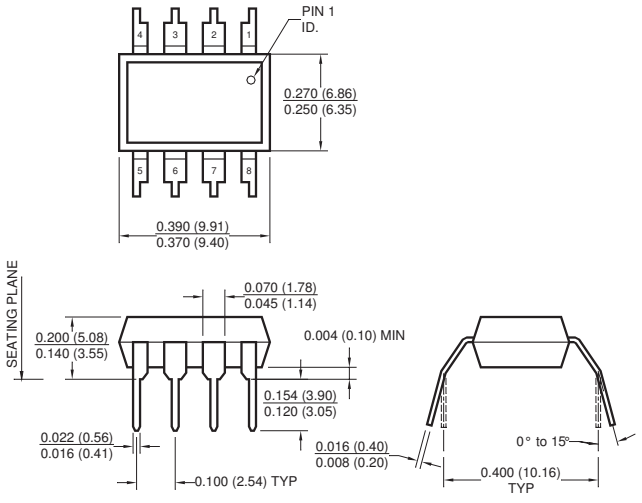
Package Dimensions (Through Hole)



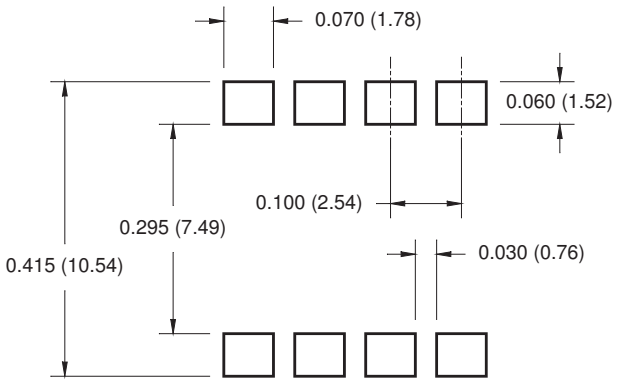
Package Dimensions (Surface Mount)



Package Dimensions (0.4"Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform



NOTE
All dimensions are in inches (millimeters)

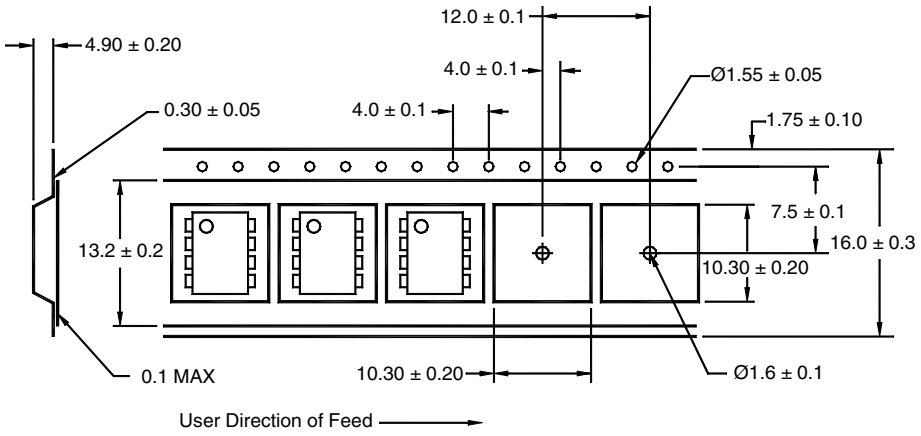
SINGLE-CHANNEL
6N137
HCPL-2601
HCPL-2611

DUAL-CHANNEL
HCPL-2630
HCPL-2631

ORDERING INFORMATION

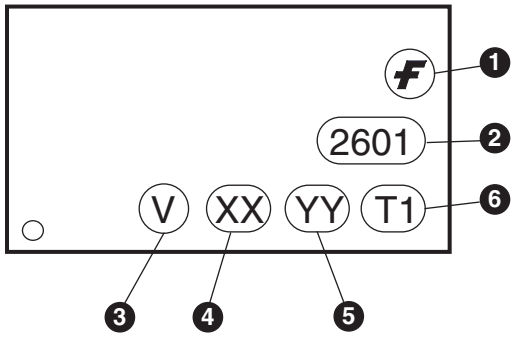
Option	Order Entry Identifier	Description
S	.S	Surface Mount Lead Bend
SD	.SD	Surface Mount; Tape and reel
W	.W	0.4” Lead Spacing

QT Carrier Tape Specifications (“D” Taping Orientation)



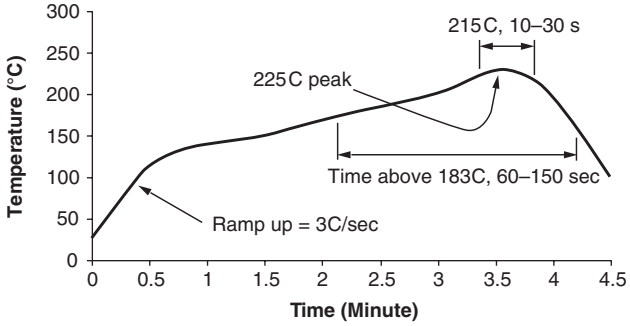
FAIRCHILD
SEMICONDUCTOR®

MARKING INFORMATION



Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., ‘03’
5	Two digit work week ranging from ‘01’ to ‘53’
6	Assembly package code

Reflow Profile



- Peak reflow temperature: 225C (package surface temperature)
- Time of temperature higher than 183C for 60–150 seconds
- One time soldering reflow is recommended

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FAST®	ISOPLANAR™	Power247™	Stealth™
ActiveArray™	FASTr™	LittleFET™	PowerEdge™	SuperFET™
Bottomless™	FPS™	MICROCOUPLER™	PowerSaver™	SuperSOT™-3
CoolFET™	FRFET™	MicroFET™	PowerTrench®	SuperSOT™-6
CROSSVOLT™	GlobalOptoisolator™	MicroPak™	QFET®	SuperSOT™-8
DOME™	GTO™	MICROWIRE™	QS™	SyncFET™
EcoSPARK™	HiSeC™	MSX™	QT Optoelectronics™	TinyLogic®
E^2CMOS™	I^2C™	MSXPro™	Quiet Series™	TINYOPTO™
EnSigna™	*i-Lo*™	OCX™	RapidConfigure™	TruTranslation™
FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
FACT Quiet Series™		OPTOLOGIC®	µSerDes™	UltraFET®
Across the board. Around the world.™		OPTOPLANAR™	SILENT SWITCHER®	VCX™
The Power Franchise®		PACMAN™	SMART START™	
Programmable Active Droop™		POP™	SPM™	

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Ordering Lead-Free Parts

In some cases during the conversion period, lead-free products must be ordered with a "_NL" suffix. Lead-free products will also be marked differently from tin-lead finished products if the assembly and test facility where they are manufactured has not been fully converted. This special order flow and marking will be used only during the transition to lead-free products. Once facilities are fully converted, lead-free products will be considered the "standard" and will not require the "_NL" suffix ordering code.

For example:

Code for standard tin-lead product: FAN8017
Code for lead-free product from a fully converted factory: FAN8017
Code for lead-free product from a factory that has not completed conversion: FAN8017_NL

Once all of Fairchild's factories producing this product are fully converted to lead-free manufacturing, all parts will have the standard marking: FAN8017.

How to order lead-free parts – Ordering Flow at FSPN Level	
Orders for parts with Lead-Free plating can be placed using the following flow or options:	

Option 1	To order a standard part with Lead-Free (Pb-Free) plating use flow NL.
	
	For example:
	`Sn/Pb part: MMBT3904`
	`Pb-Free part: MMBT3904_NL`

Option 2	To order a part with Lead-Free (Pb-Free) plating and a special flow option such as F40 (Flow 40) or D87Z (10K reel option) use flow N plus the existing flow.
	
	For example:
	`Sn/Pb part: MMBT3904_F40`
	`Pb-Free part: MMBT3904_NF40`

Option 3	To order a stamp off with Lead-Free (Pb-Free) plating

Option 3	To order a stamp-off with Lead-Free (Pb-Free) plating use N plus the remaining seven characters in the stamp-off number.
	
	Note: New stamp-off must be generated with the prefix “N?in front of the stamp-off number.
	
	For Example:
	`Sn/Pb part: 4N32_B4N001A`
	`Pb-Free part: 4N32_NB4N001A`